



General Description

The advanced trench MOS technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and converter applications.

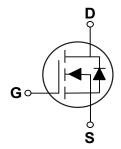
BV _{DSS}	R _{DS(ON)}	I _D		
30 V	2.2 mΩ	85 A		

Features

- $\bullet \; R_{DS(ON)} \leq 2.2 m \Omega @V_{GS} = 10 V$
- · Low Gate Charge
- · Low R_{DS(ON)}
- · Green Device Available

PPAK5X6 Pin Configuration





Applications

- Power Management in Desktop Computer
- DC/DC Converters

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	±20	V
1	Drain Current – Continuous (T _C =25°C)	85	Α
I _D	Drain Current – Continuous (T _C =100°C)	67	А
I _{DM}	Drain Current – Pulsed (NOTE 1)	250	Α
EAS	Single Pulse Avalanche Energy (NOTE 2)	151	mJ
IAS	Avalanche Current	55	Α
P_{D}	Power Dissipation (T _C =25°C) (NOTE 3)	48	W
TJ	Operating Junction Temperature Range	-55 to 150	°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
Marking Code		NC2P2	

Thermal Characteristics					
Symbol Parameter		Тур.	Max.	Unit	
R _{eJA} Thermal Resistance Junction to Ambient			50	°C/W	
$R_{ heta JC}$	Thermal Resistance Junction to Case		2.6	°C/W	





Electrical Characteristics (T_{.J}=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	30			V
I	les IDrain-Source Leakage Current	V_{DS} =24V , V_{GS} =0V , T_J =25°C			1	uA
DSS		V_{DS} =24V , V_{GS} =0V , T_{J} =55 $^{\circ}$ C			5	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	IStatic Drain-Source On-Resistance	V _{GS} =10V , I _D =20A		1.8	2.2	· mΩ
TOS(ON)		V_{GS} =4.5V , I_D =20A		2.5	3.6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.2	1.6	2.2	V
gfs	Forward Transconductance	V_{DS} =5V , I_D =20A		91		S

Dynamic and switching Characteristics

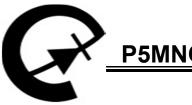
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge (4.5V)			21		
Q_{gs}	Gate-Source Charge	V_{DS} =15V , V_{GS} =10V , I_{D} =20A		12.5		nC
Q_{gd}	Gate-Drain Charge			14.5		
$T_{d(on)}$	Turn-On Delay Time			12		
T _r	Rise Time	V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω		6		nS
$T_{d(off)}$	Turn-Off Delay Time	, I _D =20A		38.5		113
T_f	Fall Time			11.5		
C _{iss}	Input Capacitance			3032		
C _{oss}	Output Capacitance	V_{DS} =15V , V_{GS} =0V , F=1MHz		1588		pF
C _{rss}	Reverse Transfer Capacitance			207		
R_g	Gate resistance	V _{GS} =0V , V _{DS} =0V , F=1MHz		1.7		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V, Force Current			85	Α
V_{SD}	Diode Forward Voltage (NOTE 1)	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V

NOTES:

- 1. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 2. The EAS data shows Max. rating. The test condition is V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =55A.
- 3. The power dissipation is limited by 150°C junction temperature.
- 4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.





Characteristics Curves

FIG.1-Typical Output Characteristics

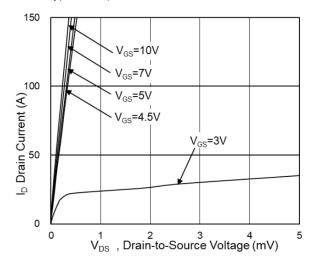


FIG.2-On-Resistance vs. G-S Voltage

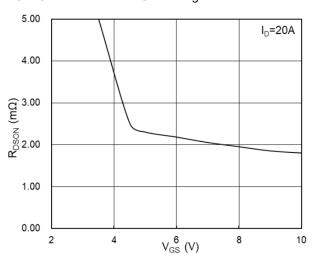


FIG.3-Source Drain Forward Characteristics

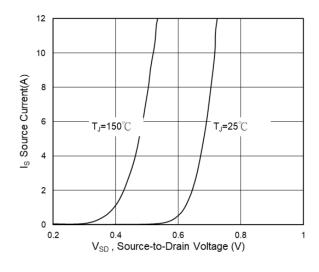


FIG.4-Gate Charge Characteristics

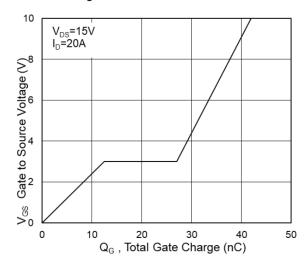


FIG.5-Normalized $V_{GS(th)}$ vs. T_J

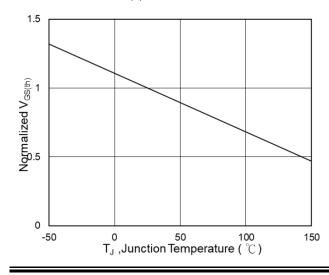
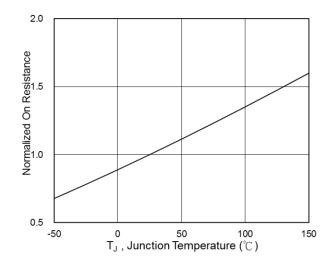


FIG.6-Normalized R_{DSON} vs. T_{J}







Characteristics Curves

FIG.7-Switching Time Waveform

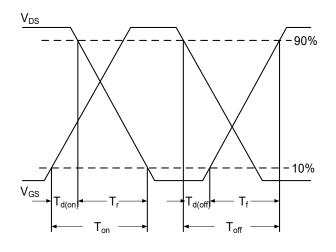
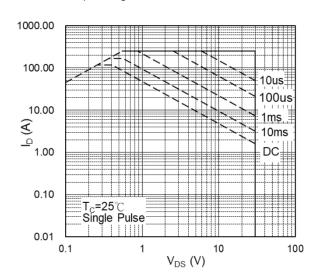
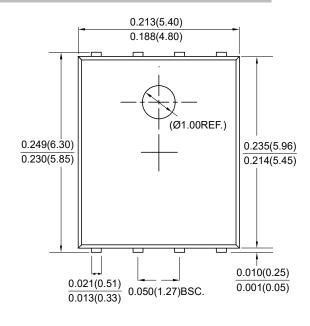
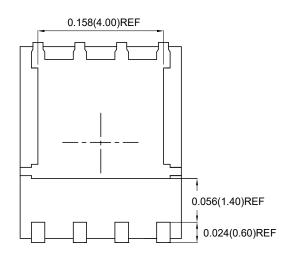


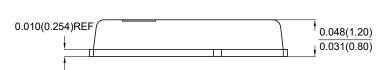
FIG.8-Safe Operating Area

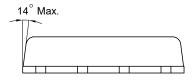


Package Outline Dimensions









PPAK5X6

Dimensions in inches and (millimeters)





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